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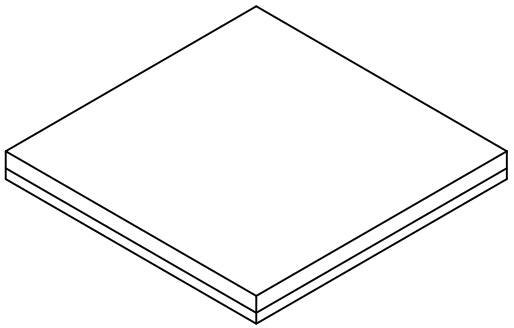
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C05891	04/20/99	E.B.	L.J.M.



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6 PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 208.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 17 X 17.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ±0.10, X.XX ±0.05, X.XXX ±0.03
ANGULAR: ±1°

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS	DATE
DRAWN L. MACKEY	04/01/99
CHECKED J. MICKSCH	04/01/99
ENG'R T. PANCZAK	04/01/99
RELEASED G. SCHULTZ	04/20/99

ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea
AMKOR Electronics, Inc. Chandler, Arizona, USA
amkor anam

TITLE: PACKAGE OUTLINE – CTBGA 208, 15.00mm X 15.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	75322	00

STRIP DWG NUMBER/REV	CUST CODE	SCALE	SHEET
N/A	N/A	SCALE: 8:1	SHEET 1 OF 3